

L Number	Hits	Search Text	DB	Time stamp
19	3785	134/57R,63,66,153,158,161,902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 11:45
20	143	134/57R,63,66,153,158,161,902.ccls. and @pd>20030619	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 11:46
21	124	((134/57R,63,66,153,158,161,902.ccls. and @pd>20030619) and (semiconductor or wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 11:50
22	49	((134/57R,63,66,153,158,161,902.ccls. and @pd>20030619) and (semiconductor or wafer or substrate)) and (holder or chuck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 11:50
23	87	118/52,53,500,501.ccls. and @pd>20030619	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/11 11:56
-	9	yuji.in. and kamikawa.in. and @pd>20030619	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 10:19
-	140	134/57R,63,66,153,158,161,902.ccls. and @pd>20030619	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 10:20
-	121	((134/57R,63,66,153,158,161,902.ccls. and @pd>20030619) and (semiconductor or wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 10:21
-	67	((134/57R,63,66,153,158,161,902.ccls. and @pd>20030619) and (semiconductor or wafer or substrate)) and (rotat\$3 or pivot\$3 or posture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 10:21
-	85	118/52,53,500,501.ccls. and @pd>20030619	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/04 12:01